Block Diagram Revision: 1.0
BOM

Item	Quantity	Reference	Value	Description	Mnf PartNum#
1	11	CB1,C2,CB4,C19,C20,C21,C22,C23,C24,C25,C26	100n	CAPC, 100NF 25V X7R 0402 +\-10%	04023C104KAT2A
2	5	CB5,C6,C7,C8,C29	1u	CAPC, 1UF 16V X5R 0402	C1005X5R1C105K
3	3	CB6,CB23,CB33	10n	CAPC, 10NF 50V X7R 0402	C0402C103K5RACTU
4	18	CB7,CB8,CB9,CB10,CB11,CB12,CB13,CB14,CB15,CB16,CB17,CB18,CB19,CB20,CB25,CB26,CB27,CB28	1u	CAPC, 1UF 6.3V X5R 0201	02016D105MAT2A
5	5	C4,CB21,CB22,CB29,CB30	0.47uF	CAPC, 0.47uF 16V X5R 0402	C1005X5R1C474K050BB
6	2	CB31,CB32	330p	CAPC, 330PF 50V C0G 0402	04025A331JAT2A
7	10	C16,CB34,C39,C40,C41,C42,C45,C46,C75,C79	10u	CAPC, 10UF 10V X7R 0805	GRM21BR71A106KE51L
8	1	C1	33n	CAPC, 33NF 50V X7R 0402	GRM155R71E333KA88D
9	3	C5,C9,C10	10u	CAPC, 10UF 25V X5R 0805	08053D106MAT2A
10	2	C17,C18	20p	CAPC, 20PF 50V C0G 0402	04025A200JAT2A
11	2	C27,C28	10p	CAPC, 10PF 50V C0G 0402	04025A100BAT2A
12	2	C30,C33	.1uF	CAPC, 2.2UF 35V X5R 0603	C1608X5R1V225K080AC
13	4	C32,C34,C37,C38	220n	CAPC, 220NF 16V X7R 0402 +\-10%	GRM155R71C224KA12
14	2	C35,C36	10n	CAPC, 10NF 10V X7R 0201	0201ZC103KAT2A
15	4	C43,C44,C56,C64	10uF	CAPC, 10uF 25V X7R 1210 +\-20%	C3225X7R1E106M250AC
16	1	C47	100uF	CAPC, 100UF, 20V, CASE D	293D107X9020D
17	2	C49,C50	0.1uF	CAPACITOR CERAMIC, 0.1UF, 25V, X5R, 10%, 0603	06033D104KAT2A
18	3	C51,C52,C54	10nF	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	GRM155R71E103KA01D
19	1	C53	1uF	CAPACITOR CERAMIC, 1UF, 16V, X5R, 10%, 0402	C1005X5R1C105K050BC
20	2	C55,C61	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	C1608X5R1C105K
21	2	DB2,DB3	SL23	DIODE, Schottky, SL23, 2A, 0.32Vfd ,SMB	SL23-E3/52T

22	1	D2	NSR1020MW2T1G	DIODE, Schottky, NSR1020MW2T1G, 1A, 0.54V@1A Vfd	NSR1020MW2T1G
23	3	D3,D4,D5	GREEN	DIODE, LED, GREEN, 0603, SMT	5988070102F
24	1	JB1	PCIEx4 Conn 180deg	CON, IO, PCIEx4, 180 deg Stright	PCIE-64-02-F-D-EM2
25	1	J1	DP3R020SU32JQ1R400	CON, IO, TBT Source, STD Mount, SMT/TH	DP3R020SU32JQ1R400
26	1	J2	RCA JACK	CON, PWR , RCA JACK, DC_003	DC_003-
27	1	J3	HEADER 5x1 TH	CON, HDR, 100mil PITCH, 5x1, TH	TSW-105-07-L-S
28	1	L1	330	Ferrite, 0603, 330Ohm@100Mhz, 0.080ohm DCR, 1.7A	BLM18KG331SN1
29	1	L2	220	Ferrite, 0402, 220ohm@100Mhz,0.35ohm DCR,0.3A	BLM15AG221SH1\N1
30	1	L4	120	Ferrite, 0402, 120Ohm@100Mhz, 0.095 DCR, 1.5A	BLM15EG121SN1
31	1	L5	0.6uH	Inductor,0.6uH,19.14mOhm DCR,5A,H=1.2mm, XFL4012	XFL4012-601MEC
32	1	L9	10uH	Inductor, Shielded, Composite, 10uH, 7.6A, 0.03 ohm, SMD	XAL6060-103MEB
33	12	TP1,PAD1,TP2,PAD2,PAD3, PAD4,PAD5,PAD6,PAD7,PA D8,PAD9,PAD10	PAD_0402	NOT A PART, TEST 0402 PAD	
34	2	QB1,Q3	2N7002	TRANS, NMOS, 0.5A, 5VGS, 3Ohm RDS, SOT23-3	2N7002/NDS7002A
35	1	QB3	MMBT2222A	TRANS, NPN, MMBT2222, SOT23, SMT	MMBT2222
36	1	Q2	FDC610PZ	TRANS, PMOS, FDC610PZ, SSOT6	FDC610PZ

37	22	RB1,RB4,RB5,RB10,RB11,R15,R16,RB18,RB19,RB21,RB23,RB25,R27,R28,R29,RB30,R30,RB31,R31,RB32,R32,RB37	100K	RESC, 100K Ohm, 0402, 1%	MC00625W04021100K
38	1	RB2	0	RESC, 0 Ohm, 0402	MC 0.0625W 0402 1% 0R
39	27	R1,R3,R4,R5,R6,R9,R10,R11,RB12,RB13,R14,RB16,RB17,R17,R18,R19,R20,R21,RB22,R24,RB33,R33,RB52,RB53,RB54,RB55,R61	10K	RESC, 10K Ohm, 0402, 0.1%	CPF0402B10KE1
40	1	RB20	100	RESC, 100 Ohm, 0402, 1%	ERJ-2RKF1000X
41	6	R8,RB24,RB35,RB36,R38,RB40	1K	RESC, 1K Ohm, 0402, 1%	MC00625W040211K
42	2	RB26,RB34	1M	RESC, 1M Ohm, 0402, 1%	MC00625W040211M
43	2	RB27,R34	12.1	RESC, 12.1 Ohm, 0402, 1%	MC00625W0402112R1
44	2	RB38,RB39	49.9	RESC, 49.9 Ohm, 0402, 1%	RC0402FR-0749R9L
45	1	RB41	11.5k	RESC, 7.32K Ohm, 0402, 1%	RC0402FR-077K32L
46	1	RB48	47K	RESC, 47K Ohm, 0402, 1%	MC00625W0402147K
47	3	RB49,RB50,RB51	330	RESC, 330 Ohm, 0402, 5%	RC0402JR-07330RL
48	1	R2	0	RESC, 0 Ohm, 0402	MC 0.0625W 0402 1% 0R
49	4	R25,R26,R35,R36	470K	RESC, 470K Ohm, 0402, 1%	MC00625W04021470K
50	1	R37	10k	RES, 10.0k ohm, 1%, 0.063W, 0402	'CRCW040210K0FKED
51	1	UB4	SN74AUP1G17	SINGLE SCHMITT-TRIGGER BUFFER GATE	SN74AUP1G17DBVR
57	2	U9,U15	TPS22920L	IC, Analog,TPS22920L,Analog Switch,8mOhm@1.05V,4	TPS22920LYZPR
58	1	U10	TPS65980_Milo	Switching Regulator	TPS65980RHFR
59	1	U11	SN74AHC1G126	Tri State Buffer-DCK package	SN74AHC1G126DCKR
60	1	U12	SN74AUP1T17	Schmitt-Trigger Buffer Gate	SN74AUP1T17DCKR
61	1	U13	TPS3700	Comparator	TPS3700DDCR

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